

**CLAIMS**

**IN THE CLAIMS**

1. (Cancelled).
2. (Cancelled).
3. (Cancelled).
4. (Cancelled).
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29. (Cancelled).
30. (Cancelled).
31. (Cancelled).
32. (Cancelled).

33. (Cancelled).

34. (Currently Amended) The ~~particulate-tape~~ method of Claim ~~32~~108, wherein said particulate tape is substantially continuous in the form of a ribbon or sheet.

35. (Currently Amended) The ~~particulate-tape~~ method of Claim ~~32~~108, wherein said single component is generally dielectric.

36. (Currently Amended) The ~~particulate-tape~~ method of Claim 35, wherein said single component includes at least one material selected from the group consisting of magnesia, alumina, silica, titania, zirconia, barium oxide, lead oxide, bismuth oxide, and a combination of the above materials.

37. (Currently Amended) The ~~particulate-tape~~ method of Claim ~~32~~108, wherein said single component is formed in a pattern corresponding to a patterned deposition electrode located on the surface of said carrier.

38. (Currently Amended) The ~~particulate-tape~~ method of Claim 37, wherein said single component is generally conductive.

39. (Currently Amended) The ~~particulate-tape~~ method of Claim 38, wherein said component includes at least one material selected from the group consisting of aluminum, silver, copper, nickel, palladium, gold, and a combination of the above materials.

40. (Cancelled).

41. (Cancelled).

42. (Cancelled).

43. (Cancelled).

44. (Cancelled).

45. (Cancelled).

46. (Cancelled).

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57. (Cancelled).

58. (Cancelled).

59. (Currently Amended) A method for producing a particulate tape, comprising the steps of:

providing a ~~tape~~ carrier which includes an electrically conductive area on at least one surface of said carrier;

electrophoretically depositing a particulate material onto said conductive area to form a component of said particulate tape; and

removing said component from said carrier.

60. (Currently Amended) The method of Claim 59, wherein said electrically conductive area forms a pattern on the surface of the ~~tape~~ carrier.

61. (Currently Amended) The method of Claim 60, further comprising the steps of:

providing a second patterned electrically conductive area on the ~~tape~~ carrier which is electrically isolated from said first patterned electrically conductive area; and

electrophoretically depositing a second component onto at least one of said first or second patterned electrically conductive areas.

62. (Previously Presented) The method of Claim 59, further comprising the step of:

laminating said electrophoretically formed component to another surface prior to removal from said carrier.

63. (Currently Amended) An apparatus for forming a particulate tape, comprising:

a tape carrier having an electrically conductive area on at least one surface, and

an electrophoretic deposition bath, wherein a component of a particulate tape may be formed by electrophoretically depositing a particulate material on said conductive surface in said bath; and

a means for removing said component from said carrier.

64. (Previously Presented) The apparatus of Claim 63, wherein said carrier is a ribbon.

65. (Previously Presented) The apparatus of Claim 63, wherein said carrier is a belt.

66. (Previously Presented) The apparatus of Claim 63, wherein said carrier is a drum.

67. (Previously Presented) The apparatus of Claim 63, wherein said carrier is a sheet.

68. (Previously Presented) The apparatus of Claim 63, wherein said carrier is a plate.

69. (Cancelled).

70. (Cancelled).

71. (Cancelled).

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73. (Cancelled).

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95. (Cancelled).

96. (Cancelled).

97. (New) The method of Claim 59, further comprising the step of:

before said removing step, applying a binder to said electrophoretically deposited component.

98. (New) The method of Claim 97, wherein said binder is dissolved in a bath used for said electrophoretic deposition and remains in the deposited component after removal from said carrier.

99. (New) The method of Claim 97, wherein said binder is sprayed onto said deposited component before said removing step.

100. (New) A method for producing an electronic device, comprising the steps of:

forming at least one component by electrophoretically depositing a particulate material on a carrier;

laminating said component to a stack of at least one particulate tape;  
and

removing said carrier from said component.

101. (New) The method of Claim 100, wherein said removing step occurs before said laminating step.

102. (New) The method of Claim 100, wherein said removing step occurs after said laminating step.

103. (New) The method of Claim 100, wherein said device includes a capacitor.

104. (New) The method of Claim 100, wherein said device includes an inductor.

105. (New) The method of Claim 100, wherein said device includes a resistor.

106. (New) The method of Claim 100, wherein said device includes a conductive interconnect structure.

107. (New) The method of Claim 100, wherein said electrophoretically deposited component includes a binder.

108. (New) A method of forming a single component particulate tape, comprising the steps of:

providing a carrier which includes an electrically conductive area on at least one surface of said carrier;

electrophoretically depositing a particulate material onto said  
conductive area to form said single component of said particulate tape; and  
removing said particulate tape from said carrier.